

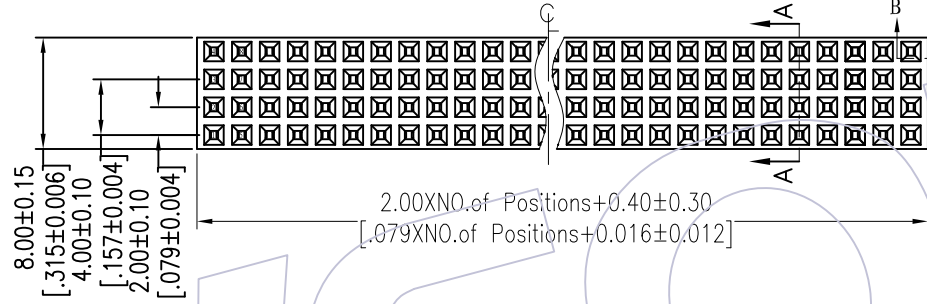
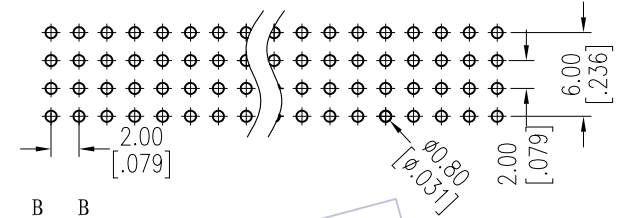
HSF

NOTES:

Current Rating: 2.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact plating: Au Or Sn over Ni
 Insulator Material: LCP+30%G.F UL94V-0

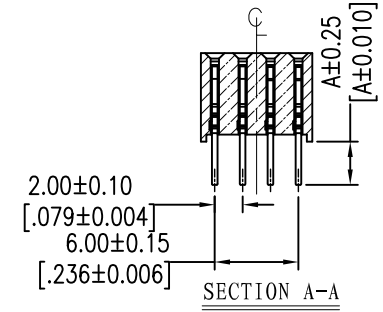
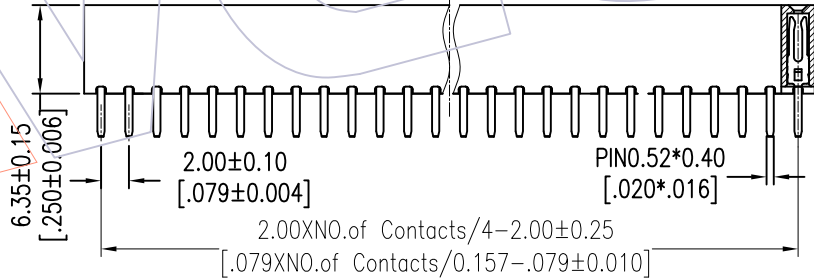
Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE±0.05)



Ordering Information

2263 - 4 XX S XX D Y N T X

- No. of Pins per ROW: 02-40PIN
- Contact Plating: G0=Gold Flash, G3=10μ"Gold, G4=15μ"Gold, G5=30μ"Gold, S0=Gold Flash/Tin, S3=10μ"Gold/Tin, S4=15μ"Gold/Tin, S5=30μ"Gold/Tin, SN=Tin, SM=Matte Tin
- Insulator: D=LCP
- Packing: T=Tube



Item	Pitch	DIM A	Mating
Standard	2.00	3.1/2.4	1215/1220
Alternate			

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A2	2013/04/26	Modify drawing	-----	x.x ±0.40	Wang	2013/04/26	UNIT	mm	2263-4XXSXXDYNTX
A1	2012/11/07	Modificat the table: DIM A 3.15--3.1/2.4	-----	x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE: FH2.0mm FOUR ROW 180° DIP H=6.35
A0	2012/07/23	NEW	-----	x.xxx ±0.15	APPROVE	DATE	SHEET	1/1	Customer NO.
				Angle ± 3°			PROJ.		
				DIM TOL					